

**IN THE ABSTRACT:**

Kindly amend the abstract to read as follows.

B1 -- In the present invention, a printed wiring board with an electronic component mounted on a circuit board in which the electronic component is provided with a heat radiating plate for conducting heat internally generated, includes a heat radiating device mounted at a position corresponding to the electronic component on a rear surface of the circuit board. --

**IN THE SPECIFICATION:**

Kindly replace pages 8-15 of the specification with the substitute pages 8-15 that is submitted herewith (a red-lined version also is submitted for the Examiner's convenience).

**IN THE CLAIMS:**

Please cancel claims 4 and 5 without prejudice and disclaimer.

Kindly amend pending claims 6 and 15 to read as follows:

B2 6. (Twice Amended) The printed wiring board according to claim 1, wherein said heat radiating means is made of metal, and is provided, on a rear side thereof, with a plated layer which is able to be brought into contact with said circuit board and on a front side thereof, with a plurality of fins for radiating heat.

B3 15. (Amended) A printed wiring board, comprising:  
a circuit board;  
an electronic component mounted on said circuit board and including a heat radiating plate for conducting heat internally generated;